

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1	knappe near uwe.in.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD_B
2	BRS	L2	0	raeblger near jan.in.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD_B
3	BRS	L3	9	schulze near uwe.in.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD_B
4	BRS	L4	50930	(alignment) near15 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD_B

	Type	L #	Hits	Search Text	DBs
5	BRS	L5	5895	(alignment) near15 (first) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B
6	BRS	L6	3716	(alignment) near15 (first) near (substrate or wafer) near25 (second) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B
7	BRS	L7	1	(alignment) near15 (first) near (substrate or wafer) near25 (second) near (substrate or wafer) near35 (setpoint)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B
8	BRS	L8	0	(alignment) near15 (first) near (substrate or wafer) near25 (second) near (substrate or wafer) near35 (set near point)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B

	Type	L #	Hits	Search Text	DBs
9	BRS	L9	629	(alignment) near15 (first) near (substrate or wafer) near25 (second) near (substrate or wafer) near35 (position or motion or mov\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
10	BRS	L10	1	(alignment) near15 (first) near (substrate or wafer) near25 (characteristic\$1) near25 (second) near (substrate or wafer) near35 (position or motion or mov\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
11	BRS	L11	82	(alignment) near15 (first) near (substrate or wafer) near25 (after or during) near25 (second) near (substrate or wafer) near35 (position or motion or mov\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
12	BRS	L12	59	(alignment) near15 (first) near (substrate or wafer) near25 (after) near25 (second) near (substrate or wafer) near35 (position or motion or mov\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
13	BRS	L13	0	(alignment) near15 (first) near (substrate or wafer) near25 (after) near25 (align\$3 near second) near (substrate or wafer) near35 (position or motion or mov\$3)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B
14	BRS	L14	2	(first) near (substrate or wafer) near25 (after) near25 (align\$3 near second) near (substrate or wafer) near35 (position or motion or mov\$3)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B
15	BRS	L15	38	(substrate or wafer) near25 (after) near25 (align\$3 near second) near (substrate or wafer) near35 (position or motion or mov\$3)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B
16	BRS	L16	84	(substrate or wafer) near25 (after) near25 (align\$3 near second) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TD B

	Type	L #	Hits	Search Text	DBs
17	BRS	L17	0	(substrate or wafer) near25 (after) near25 (align\$3 near second) near (substrate or wafer) same (setpoint)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
18	BRS	L18	0	(substrate or wafer) near25 (after) near25 (align\$3 near second) near (substrate or wafer) and (setpoint)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
19	BRS	L19	72	(after) near25 (align\$3 near second) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
20	BRS	L20	1	(setpoint) near25 (align\$3 near second) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
21	BRS	L21	2	(setpoint) near25 (align\$3) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
22	BRS	L22	6	(set near point) near25 (align\$3) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
23	BRS	L23	0	(set-point) near25 (align\$3) near (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
24	BRS	L24	218	(setpoint) near25 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
25	BRS	L25	59	24 and (align\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
26	BRS	L26	17	(setpoint) near25 (first or second) near5 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
27	BRS	L27	80	(set near point) near25 (first or second) near5 (substrate or wafer)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
28	BRS	L28	20	27 and (align\$4)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B